File View Edit Tools Window Help

- (408215) (mcm (multi adj chip adj module)) (stack$4 near2 (package chip module))
- (682754) cavity
- (6929277) (open$5 via hole aperture perforat$4)
- (408517) (mcm (multi adj chip adj module)) (stack$4 near2 (package chip module)) (
- (683198) cavity
- (30232) frustoconical
- (30534) frustocon$5
- (83681) frustocon$5 frusto adj conic$2
- (1134474) carrier
- (299935) (((printed adj circuit PC wiring) adj (board card module)) pcb PWB mot
- (8877) carrier near9 cavity
- (1747) (carrier near9 cavity) with ((open$5 via hole aperture perforat$4) □)
- (7017863) through therethrough
- (1891531) ((open$5 via hole aperture perforat$4) □) near6 (through therethrough)
- (463) ((carrier near9 cavity) with ((open$5 via hole aperture perforat$4) □
- (157) 14.clm.
- (2864464) (encapsula$3 encapsulation mold$3 resin epoxy potting gel)
- (312137) 16.clm.
- (20) 14.clm. same 16.clm.
- (74) (((carrier near9 cavity) with ((open$5 via hole aperture perforat$4) □
- (408517) (mcm (multi adj chip adj module)) (stack$4 near2 (package chip module)) (
- (16) ((((carrier near9 cavity) with ((open$5 via hole aperture perforat$4) □
- (23168455) (@ad @pd) < 19980630
- (8) ((((carrier near9 cavity) with ((open$5 via hole aperture perforat$4) □
- (7) ("4894706" | "4953005" | "5237204" | "5343366" | "5376825" | "5594275
- (32) 5608265.URPN.

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DBs USPAT, US-PGPUB, EPO, JPO, DERWENT, IBM_TDB   ☑ Plurals

Default operator: OR   ☑ Highlight all hit terms initially

(((((carrier near9 cavity) with ((open$5 via hole aperture perforat$4)
)) with (((open$5 via hole aperture perforat$4)
) near6 (through therethrough))) same ((encapsula$3 encapsulation mold$3 resin epoxy potting gel)
)) and ((mcm (multi adj chip adj module)) (stack$4 near2 (package chip module)) ("3-d" 3D three adj dimension$4)
)) and (((@ad @pd) < 19980630)

April 7 2004

#	↓↑		Inventor	Document I	Issue	P	Title	Current	Current XR	Retrieval	S	C	P		3			Image Doc.	P
1		☑	Senba, Naoji	US 6188127	2001	1	Semiconductor packing stack module and me	257/686	257/685;		☑	□	□	□	□	□	□	US 618812	□
2		□	Covell, II, Ja	US 5961032	1999	0	Method of fabrication of a multi-component s	228/254	228/180.22;		☑	□	□	□	□	□	□	US 596103	□
3		□	Kata, Keiichir	US 5759873	1998	1	Method of manufacturing chip-size package-t	438/118	257/E21.51		☑	□	□	□	□	□	□	US 575987	□
4		□	Tsuru, Yoshiy	US 5688408	1997	2	Multilayer printed wiring board	216/17	216/18;		☑	□	□	□	□	□	□	US 568840	□
5		□	Tsuru, Yoshiy	US 5562971	1996	2	Multilayer printed wiring board	428/209	174/255;		☑	□	□	□	□	□	□	US 556297	□
6		□	Leveque, Den	US 5198793	1993	1	Electric control apparatus comprising integra	338/172	200/522;		☑	□	□	□	□	□	□	US 519879	□
7		□	Utsumi, Kazu	US 4766671	1988	2	Method of manufacturing ceramic electronic	29/848	156/89.12;		☑	□	□	□	□	□	□	US 476667	□
8		□	Burry, Steph	US 4413967	1983	1	Apparatus for producing uniform density and	425/149			☑	□	□	□	□	□	□	US 441396	□
9		□	Burry, Steph	US 4376085	1983	1	Method for producing uniform density and w	264/40.	264/104;		☑	□	□	□	□	□	□	US 437808	□

Ready